

# N-channel 25 V 6.1 m $\Omega$ logic level MOSFET in LFPAK using NextPower technology

Rev. 2 — 31 October 2011

**Product data sheet** 

## 1. Product profile

#### 1.1 General description

Logic level enhancement mode N-channel MOSFET in LFPAK package. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

#### 1.2 Features and benefits

- High reliability Power SO8 package, qualified to 175°C
- Low parasitic inductance and resistance
- Optimised for 4.5V Gate drive utilising NextPower Superjunction technology
- Ultra low QG, QGD, & QOSS for high system efficiencies at low and high loads

#### 1.3 Applications

- DC-to-DC converters
- Load switching

Synchronous buck regulator

#### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C	-	-	25	V
I <sub>D</sub>	drain current	$T_{mb}$ = 25 °C; $V_{GS}$ = 10 V; see <u>Figure 1</u>	-	-	73	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	-	58	W
Tj	junction temperature		-55	-	175	°C
Static char	acteristics					
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C};$ see <u>Figure 12</u>	-	6.7	7.9	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 12</u>	-	5.1	6.1	mΩ
Dynamic c	Dynamic characteristics					
$Q_{GD}$	gate-drain charge	$V_{GS} = 4.5 \text{ V}; I_D = 20 \text{ A}; V_{DS} = 12 \text{ V};$	-	2.6	-	nC
Q <sub>G(tot)</sub>	total gate charge	see Figure 14; see Figure 15	-	9	-	nC



## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source	mb	D
3	S	source		
4	G	gate	[q]	
mb	D	mounting base; connected to drain	1 2 3 4	mbb076 S

SOT669 (LFPAK; Power-SO8)

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN6R0-25YLB	LFPAK; Power-SO8	plastic single-ended surface-mounted package; 4 leads	SOT669

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C	-	25	V
$V_{DGR}$	drain-gate voltage	25 °C ≤ $T_j$ ≤ 175 °C; $R_{GS}$ = 20 kΩ	-	25	V
$V_{GS}$	gate-source voltage		-20	20	V
$I_D$	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C}; \text{ see } \frac{\text{Figure 1}}{\text{Model}}$	-	73	Α
		$V_{GS} = 10 \text{ V; } T_{mb} = 100 \text{ °C; see } \frac{\text{Figure 1}}{}$	-	52	Α
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 \text{ °C}$ ; see Figure 4	-	292	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	58	W
T <sub>stg</sub>	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
T <sub>sld(M)</sub>	peak soldering temperature		-	260	°C
$V_{ESD}$	electrostatic discharge voltage	MM (JEDEC JESD22-A115)	220	-	V
Source-drain	diode				
Is	source current	T <sub>mb</sub> = 25 °C	-	53	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \ \mu s$ ; $T_{mb} = 25 \ ^{\circ}C$	-	292	Α
Avalanche ru	ggedness				
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; $I_D$ = 73 A; $V_{sup}$ ≤ 25 V; unclamped; $R_{GS}$ = 50 Ω; see Figure 3	-	15	mJ

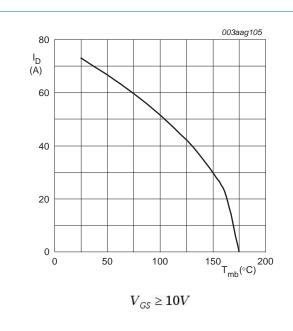


Fig 1. Continuous drain current as a function of mounting base temperature

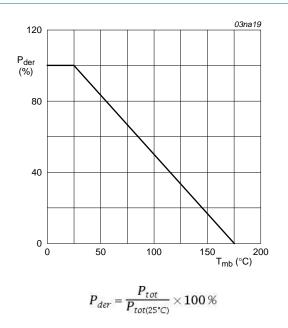
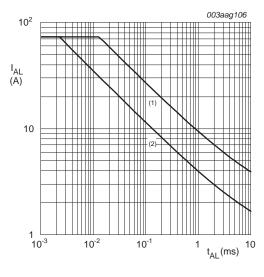


Fig 2. Normalized total power dissipation as a function of mounting base temperature



(1)  $T_{j (init)} = 25^{\circ}C$ ; (2)  $T_{j (init)} = 100^{\circ}C$ 

Fig 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

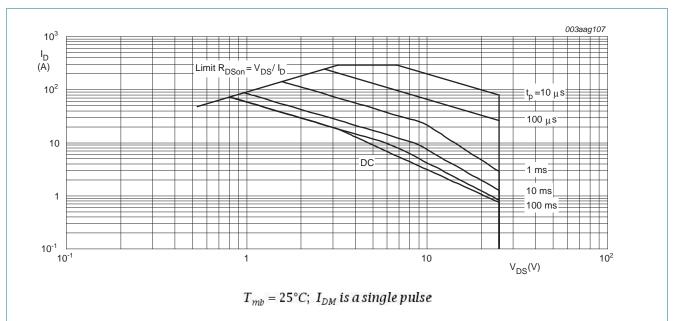
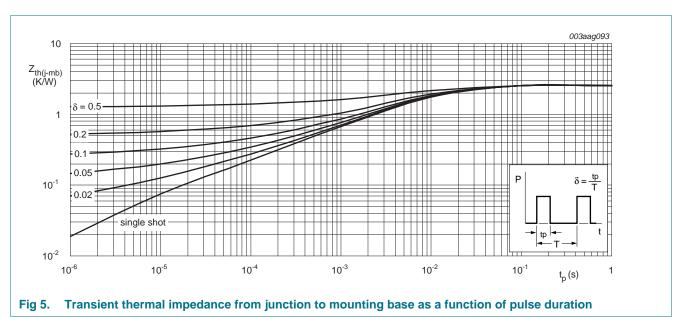


Fig 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 5	-	2.35	2.57	K/W



## 6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
•	racteristics	23.74.110.10		٠,٢٠	ax	Jint
V <sub>(BR)DSS</sub>	drain-source breakdown	$I_D = 250 \mu A; V_{GS} = 0 V; T_i = 25 °C$	25	-	-	V
- (OU)UO)	voltage	$I_D = 250 \mu\text{A};  V_{GS} = 0  \text{V};  T_i = -55  ^{\circ}\text{C}$	22.5	-	-	V
V <sub>GS(th)</sub> gate-source threshold voltage		1.05	1.42	1.95	V	
		I <sub>D</sub> = 10 mA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>i</sub> = 150 °C	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-	-	2.25	V
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 25 \text{ V}; V_{GS} = 0 \text{ V}; T_i = 25 \text{ °C}$	-	-	1	μA
D00	3	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V; T <sub>i</sub> = 150 °C	-	-	100	μA
I <sub>GSS</sub>	gate leakage current	$V_{GS} = 16 \text{ V}; V_{DS} = 0 \text{ V}; T_i = 25 \text{ °C}$	-	-	100	nA
-000	gane reamings can em	$V_{GS} = -16 \text{ V}; V_{DS} = 0 \text{ V}; T_i = 25 \text{ °C}$	-	-	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C};$ see Figure 12	-	6.7	7.9	mΩ
		$V_{GS} = 4.5 \text{ V}; I_D = 20 \text{ A}; T_j = 150 °C;$ see Figure 12; see Figure 13	-	-	13	mΩ
	$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 25 \text{ °C};$ see <u>Figure 12</u>	-	5.1	6.1	mΩ	
		$V_{GS} = 10 \text{ V}; I_D = 20 \text{ A}; T_j = 150 °C;$ see <u>Figure 12</u> ; see <u>Figure 13</u>	-	-	10.1	mΩ
$R_G$	internal gate resistance (AC)	f = 1 MHz	-	1.62	3.24	Ω
Dynamic (	characteristics					
Q <sub>G(tot)</sub> total gate charge	total gate charge	$I_D = 20 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; see Figure 14; see Figure 15	-	19.3	-	nC
		$I_D = 20 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; $V_{GS} = 4.5 \text{ V}$ ; see Figure 14; see Figure 15	-	9	-	nC
		$I_D = 0 A; V_{DS} = 0 V; V_{GS} = 10 V$	-	17.7	-	nC
$Q_{GS}$	gate-source charge	$I_D = 20 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; $V_{GS} = 4.5 \text{ V}$ ;	-	2.6	-	nC
Q <sub>GS(th)</sub>	pre-threshold gate-source charge	see <u>Figure 14</u> ; see <u>Figure 15</u>	-	1.9	-	nC
Q <sub>GS(th-pl)</sub>	post-threshold gate-source charge		-	0.7	-	nC
$Q_{GD}$	gate-drain charge		-	2.6	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 20 \text{ A}$ ; $V_{DS} = 12 \text{ V}$ ; see Figure 14; see Figure 15	-	2.44	-	V
C <sub>iss</sub>	input capacitance	$V_{DS} = 12 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz};$	-	1099	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; see <u>Figure 16</u>	-	337	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	99	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 12 \text{ V}; R_L = 0.6 \Omega; V_{GS} = 4.5 \text{ V};$	-	16	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 4.7 \Omega$	-	17	-	ns
	turn off dolay time		_	30	_	ns
t <sub>d(off)</sub>	turn-off delay time			00		

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Table 6. Characteristics ... continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$Q_{oss}$	output charge	$V_{GS} = 0 \text{ V}; V_{DS} = 12 \text{ V}; f = 1 \text{ MHz}$	-	6.6	-	nC
Source-drain diode						
$V_{SD}$	source-drain voltage	$I_S = 20 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 17</u>	-	0.85	1.1	V
t <sub>rr</sub>	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s};$	-	27	-	ns
Q <sub>r</sub>	recovered charge	$V_{GS} = 0 \text{ V}; V_{DS} = 12 \text{ V}$	-	18	-	nC
t <sub>a</sub>	reverse recovery rise time	$V_{GS} = 0 \text{ V}; I_S = 20 \text{ A};$	-	15	-	ns
t <sub>b</sub>	reverse recovery fall time	$dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{DS} = 12 \text{ V};$ see Figure 18	-	12	-	ns

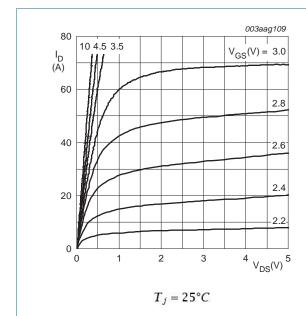
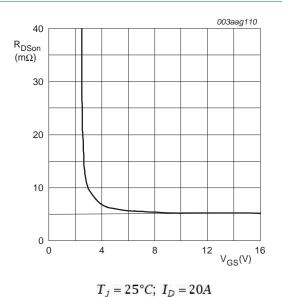


Fig 6. Output characteristics; drain current as a function of drain-source voltage; typical values



1j = 23 C, 1<sub>D</sub> = 2021

Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

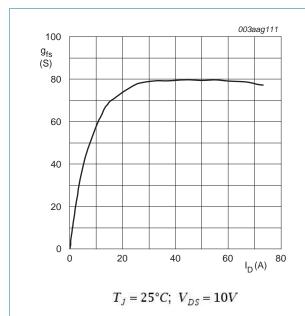
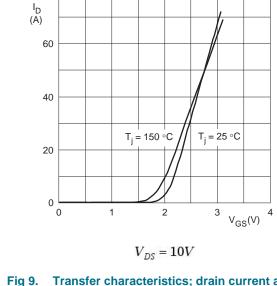


Fig 8. Forward transconductance as a function of drain current; typical values



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Fig 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

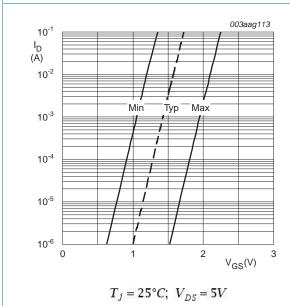


Fig 10. Sub-threshold drain current as a function of gate-source voltage

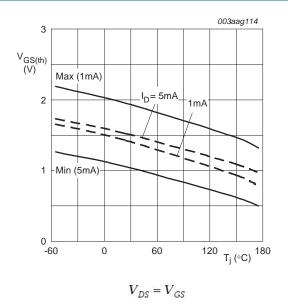


Fig 11. Gate-source threshold voltage as a function of junction temperature

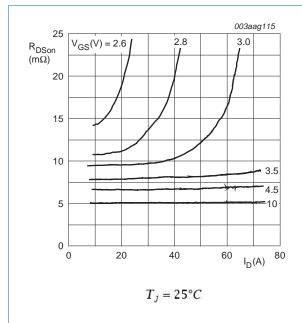


Fig 12. Drain-source on-state resistance as a function of drain current; typical values

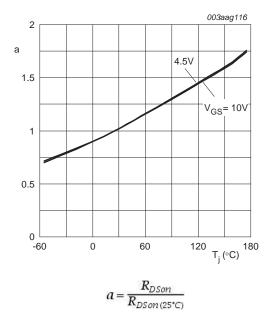


Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature

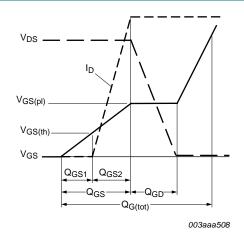
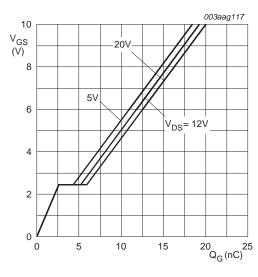


Fig 14. Gate charge waveform definitions



 $T_j = 25^{\circ}C; \ I_D = 20A$ 

Fig 15. Gate-source voltage as a function of gate charge; typical values

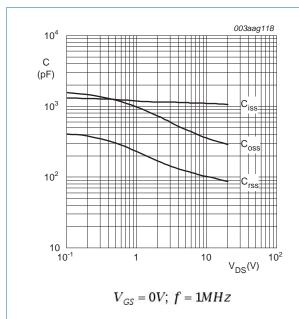


Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

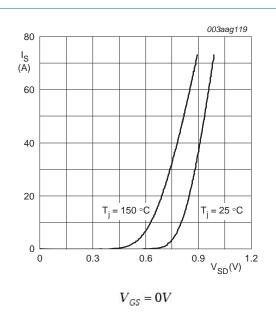


Fig 17. Source current as a function of source-drain voltage; typical values

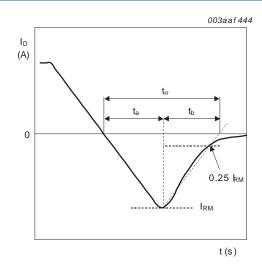
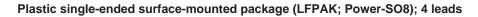


Fig 18. Reverse recovery timing definition

## 7. Package outline



SOT669

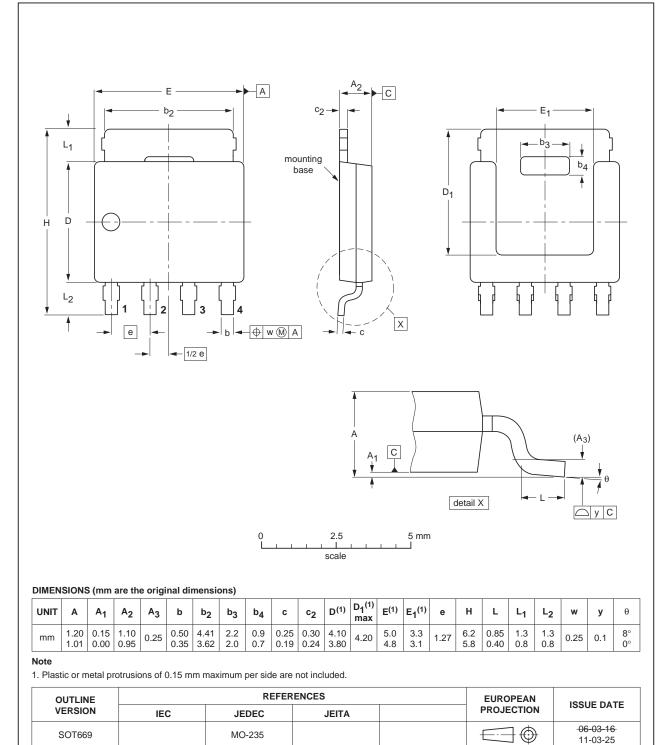


Fig 19. Package outline SOT669 (LFPAK; Power-SO8)

N-channel 25 V 6.1 mΩ logic level MOSFET in LFPAK using NextPower technology

## 8. Revision history

#### Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN6R0-25YLB v.2	20111031	Product data sheet	-	PSMN6R0-25YLB v.1
Modifications:	<ul> <li>Status changed from</li> </ul>	om preliminary to product.		
	<ul> <li>Various changes to</li> </ul>	content.		
PSMN6R0-25YLB v.1	20110908	Preliminary data sheet	-	-

#### N-channel 25 V 6.1 mΩ logic level MOSFET in LFPAK using NextPower technology

### 9. Legal information

#### 9.1 Data sheet status

Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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## **Nexperia**

## PSMN6R0-25YLB

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